



DOCKET NO. CHITTIPEDDI 59-108

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Sailesh Chittipeddi, *et al.*

Serial No.: 09/467,253

Filed: December 20, 1999

For: WIRE BONDING METHOD FOR COPPER INTERCONNECTS
IN SEMICONDUCTOR DEVICES

Group No.: 2823

Examiner: Estrada, Michelle

Commissioner for Patents
Washington, D. C. 20231

Sir:

2823

PATENT #19
RECEIVED 105
JUN 19 2002 J. M. Miller
TC 2800 MAIL ROOM 8/22/02

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on <u>June 19, 2002</u> (Date)	
(Printed or typed name of person signing the certificate) <u>Elizabeth C. Ramirez</u>	
(Signature of the person signing the certificate) <u>Elizabeth C. Ramirez</u>	
(Date of Signature) <u>June 19, 2002</u>	

INFORMATION DISCLOSURE STATEMENT

In accordance with 37 C.F.R. §1.56 and the provisions of 37 C.F.R. §§1.97 and 1.98 and §609 of the Manual of Patent Examining Procedure, Applicant hereby makes a disclosure of the patents, publications and other information listed below and on the accompanying form PTO-1449, which may be potentially material to the patentability of the invention disclosed in the above-referenced application. Pursuant to § 1.97(e) the Applicant hereby states that each item of information contained in the information disclosure statement was cited in a communication from

a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.

<u>U.S. Patent No.</u>	<u>Inventor</u>	<u>Date</u>
4,622,576	Buynoski	November 11, 1986
5,455,195	Ramsey et al.	October 3, 1995

<u>Foreign Patent No.</u>	<u>Country</u>	<u>Date</u>
903,476	GB	Aug. 15, 1962
1,294,770	GB	1 Nov. 1972
WO 00/59029	PCT	10/05/00
JP1-255234	JP	1989-10-12
JP62-216339	JP	1987-09-22

Applicant hereby certifies that each item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the statement.

As attorney for the Applicant, I am signing below on the basis of the information supplied by an individual designated in § 1.56(c).

Respectfully submitted,

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Date: June 11, 2002

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